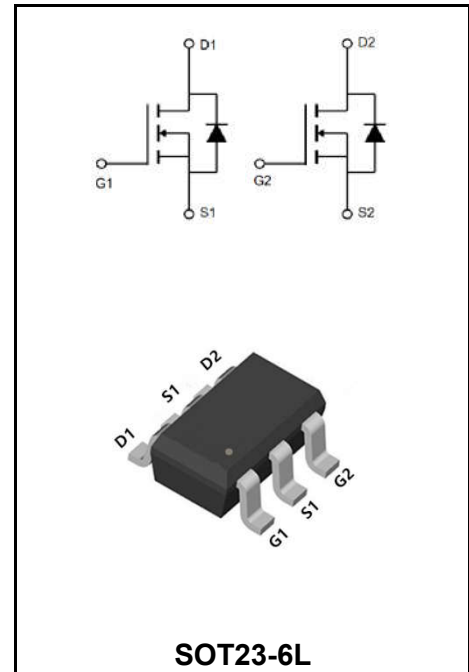


30V N+N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

I_D	3.6A
V_{DSS}	30V
$R_{DS(on)-typ}(@V_{GS}=10V)$	<60mΩ (Type:35 mΩ)
$R_{DS(on)-typ}(@V_{GS}=4.5V)$	<75mΩ (Type:52 mΩ)



Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW3H03LI	SOT23-6L	H26D	3000PCS/Tape

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current, $V_{GS} @ 10 V^1 @ T_A=25^{\circ}C$	I_D	3.6	A
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_A=70^{\circ}C$	I_D	2.7	A
Pulsed Drain Current ²	I_{DM}	18.4	A
Total Power Dissipation ³ @ $T_A = 25^{\circ}C$	P_D	1	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	125	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	80	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250 \mu A$	BV_{DSS}	30	-	-	V
BVDSS Temperature Coefficient	Reference to 25°C , $I_D = 1mA$	$\Delta BV_{DSS} / \Delta T_J$	-	0.023	-	V/°C
Static Drain-Source On-Resistance ²	$V_{GS} = 10V, I_D = 3.1A$	$R_{DS(ON)}$	-	35	60	mΩ
	$V_{GS} = 4.5V, I_D = 2A$		-	52	75	
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	$V_{GS(th)}$	1.0	1.5	2.5	V
$V_{GS(th)}$ Temperature Coefficient		$\Delta V_{GS(th)}$	-	-4.2	-	mV/°C
Drain-Source Leakage Current	$V_{DS} = 24V, V_{GS} = 0V,$ $T_J = 25^\circ C$	I_{DSS}	-	-	1	uA
	$V_{DS} = 24V, V_{GS} = 0V,$ $T_J = 55^\circ C$		-	-	5	
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I_{GSS}	-	-	±100	nA
Forward Transconductance	$V_{DS} = 5V, I_D = 4A$	G_{fs}	-	7	-	S
Gate Resistance	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	R_g	-	2.3	4.6	Ω
Total Gate Charge (4.5V)	$V_{DS} = 15V, V_{GS} = 4.5V,$ $I_D = 4A$	Q_g	-	5.0	6.9	nC
Gate-Source Charge		Q_{gs}	-	1.1	2.2	
Gate-Drain Charge		Q_{gd}	-	2.6	2.8	
Turn-On delay time	$V_{DD} = 15V, V_{GS} = 10V, R_g = 3.3\Omega,$ $I_D = 4A$	$T_d(on)$	-	2	4	nS
Rise Time		T_r	-	34.4	62	
Turn-Off Delay Time		$t_d(OFF)$	-	13.2	26	
Fall Time		T_f	-	4.8	9.6	
Input Capacitance	$V_{DS} = 15V, V_{GS} = 0V,$ $f = 1MHz$	C_{iss}	-	420	582	pF
Output Capacitance		C_{oss}	-	60	87	
Reverse Transfer Capacitance		C_{rss}	-	53	71	
Continuous Source Current ^{1,4}	$V_G = V_D = 0V, \text{ Force Current}$	I_S	-	-	4.6	A
Pulsed Source Current ^{2,4}		I_{SM}	-	-	18.4	A
Diode Forward Voltage ²	$V_{GS} = 0V, I_S = 1A, T_J = 25^\circ C$	V_{SD}	-	-	1.2	V
Reverse Recovery Time	$I_F = 4A, di/dt = 100A/\mu s,$ $T_J = 25^\circ C$	t_{rr}	-	8.7	-	nS
Reverse Recovery Charge		Q_{rr}	-	2.3	-	nC

Note :

1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

3 .The power dissipation is limited by 150°C junction temperature

4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

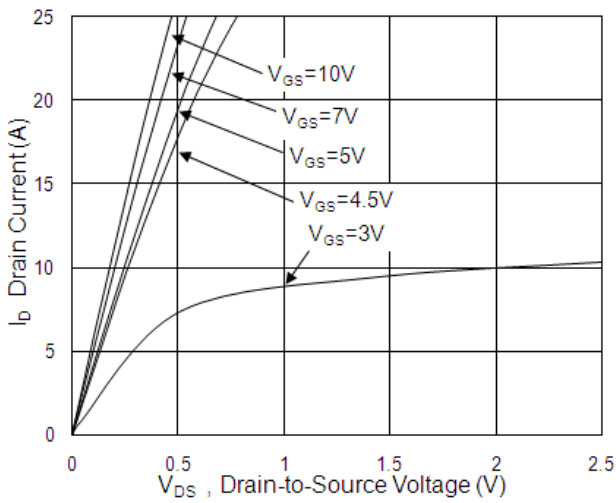


Fig.1 Typical Output Characteristics

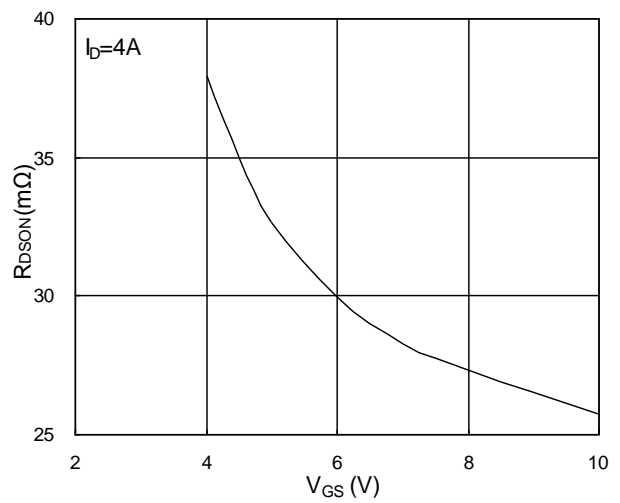


Fig.2 On-Resistance vs. Gate-Source

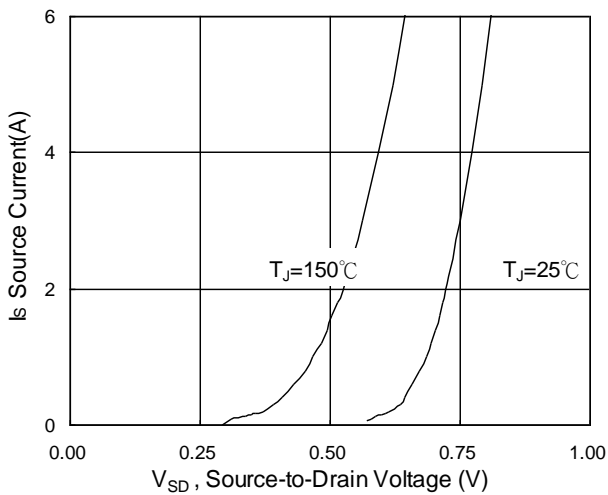


Fig.3 Forward Characteristics Of Reverse

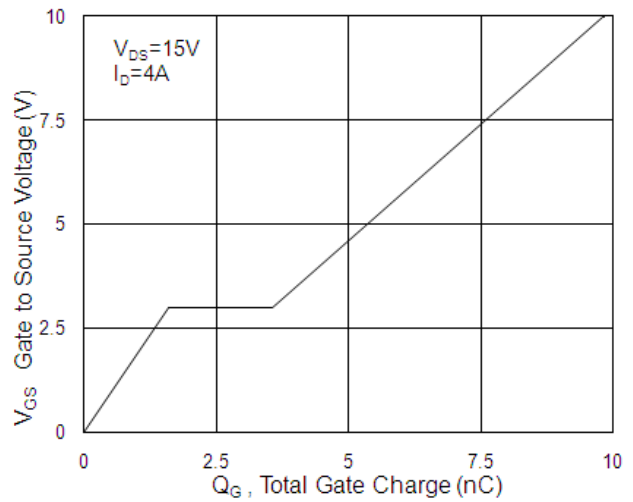


Fig.4 Gate-Charge Characteristics

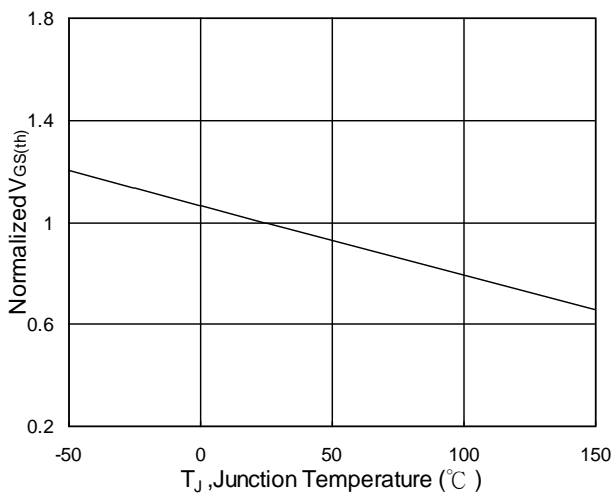


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

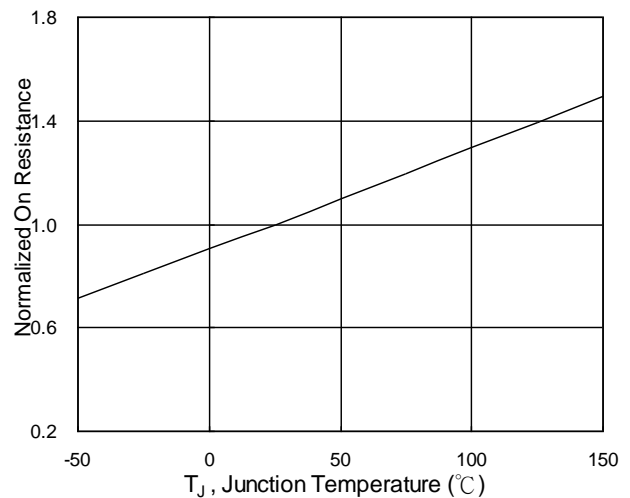


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Ratings and Characteristic Curves

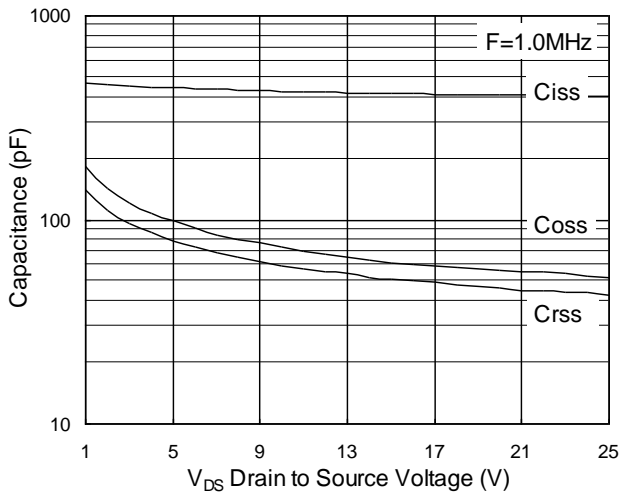


Fig.7 Capacitance

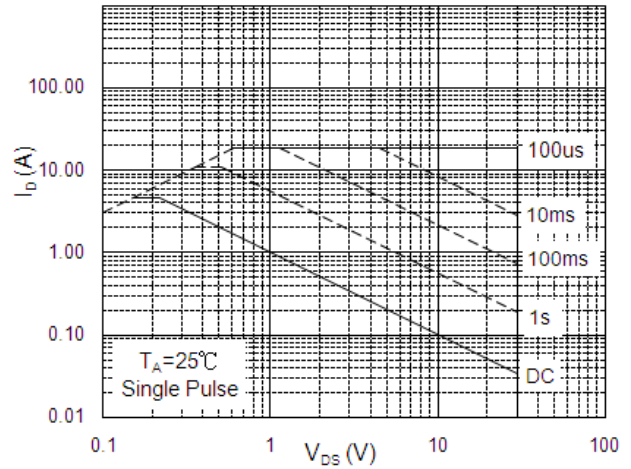


Fig.8 Safe Operating Area

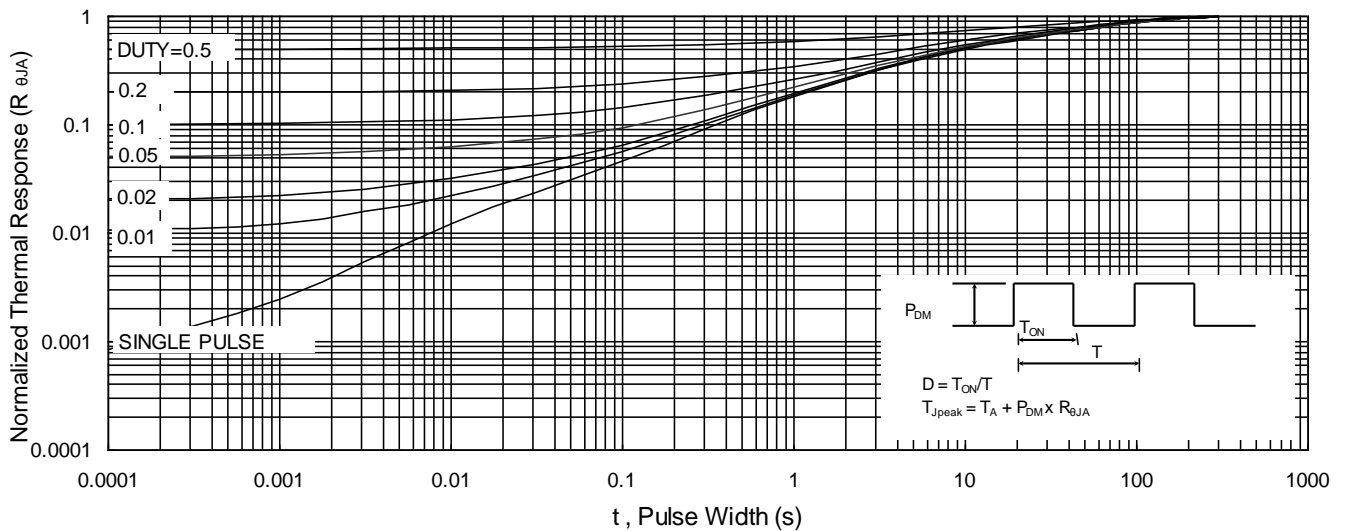


Fig.9 Normalized Maximum Transient Thermal Impedance

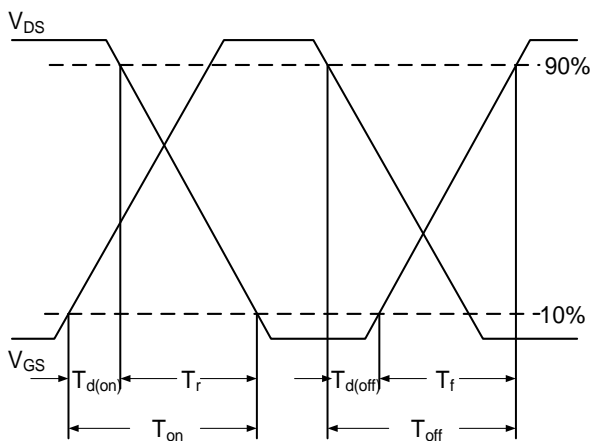


Fig.10 Switching Time Waveform

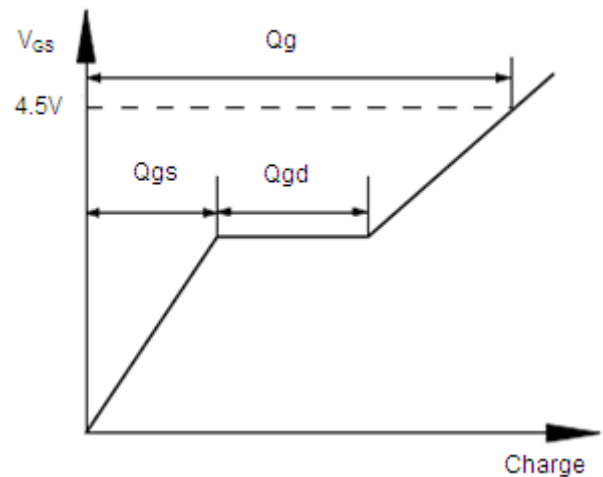


Fig.11 Gate Charge Waveform

SOT23-6L

